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"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	8051
Core Size	8-Bit
Speed	48MHz
Connectivity	EBI/EMI, I²C, LINbus, SPI, UART/USART
Peripherals	CapSense, DMA, POR, PWM, WDT
Number of I/O	25
Program Memory Size	32KB (32K x 8)
Program Memory Type	FLASH
EEPROM Size	1K x 8
RAM Size	4K x 8
Voltage - Supply (Vcc/Vdd)	1.71V ~ 5.5V
Data Converters	A/D 16x20b; D/A 4x8b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	48-BSSOP (0.295", 7.50mm Width)
Supplier Device Package	48-SSOP
Purchase URL	https://www.e-xfl.com/product-detail/infineon-technologies/cy8c3845pve-173

USBIO, D+

Provides D+ connection directly to a USB 2.0 bus. May be used as a digital I/O pin; it is powered from VDDD instead of from a VDDIO. Pins are Do Not Use (DNU) on devices without USB.

USBIO, D–

Provides D– connection directly to a USB 2.0 bus. May be used as a digital I/O pin; it is powered from VDDD instead of from a VDDIO. Pins are Do Not Use (DNU) on devices without USB.

VCCA.

Output of the analog core regulator or the input to the analog core. Requires a 1uF capacitor to VSSA. The regulator output is not designed to drive external circuits. **Note that if you use the device with an external core regulator (externally regulated mode), the voltage applied to this pin must not exceed the allowable range of 1.71 V to 1.89 V.** When using the internal core regulator, (internally regulated mode, the default), do not tie any power to this pin. For details see Power System on page 29.

VCCD.

Output of the digital core regulator or the input to the digital core. The two VCCD pins must be shorted together, with the trace between them as short as possible, and a 1uF capacitor to VSSD. The regulator output is not designed to drive external circuits. **Note that if you use the device with an external core regulator (externally regulated mode), the voltage applied to this pin must not exceed the allowable range of 1.71 V to 1.89 V.** When using the internal core regulator (internally regulated mode, the default), do not tie any power to this pin. For details see Power System on page 29.

VDDA

Supply for all analog peripherals and analog core regulator. VDDA must be the highest voltage present on the device. All other supply pins must be less than or equal to VDDA.

VDDD

Supply for all digital peripherals and digital core regulator. VDDD must be less than or equal to VDDA.

VSSA

Ground for all analog peripherals.

VSSD

Ground for all digital logic and I/O pins.

VDDIO0, VDDIO1, VDDIO2, VDDIO3

Supply for I/O pins. Each VDDIO must be tied to a valid operating voltage (1.71 V to 5.5 V), and must be less than or equal to VDDA.

$\overline{\text{XRES}}$ (and configurable $\overline{\text{XRES}}$)

External reset pin. Active low with internal pull-up. Pin P1[2] may be configured to be a XRES pin; see "Nonvolatile Latches (NVLs)" on page 22.

4. CPU

4.1 8051 CPU

The CY8C38 devices use a single cycle 8051 CPU, which is fully compatible with the original MCS-51 instruction set. The CY8C38 family uses a pipelined RISC architecture, which executes most instructions in 1 to 2 cycles to provide peak performance of up to 33 MIPS with an average of 2 cycles per instruction. The single cycle 8051 CPU runs ten times faster than a standard 8051 processor.

The 8051 CPU subsystem includes these features:

- Single cycle 8051 CPU
- Up to 64 KB of flash memory, up to 2 KB of EEPROM, and up to 8 KB of SRAM
- 512-byte instruction cache between CPU and flash
- Programmable nested vector interrupt controller
- DMA controller
- Peripheral HUB (PHUB)
- External memory interface (EMIF)

4.2 Addressing Modes

The following addressing modes are supported by the 8051:

- Direct Addressing: The operand is specified by a direct 8-bit address field. Only the internal RAM and the SFRs can be accessed using this mode.
- Indirect Addressing: The instruction specifies the register which contains the address of the operand. The registers R0 or R1 are used to specify the 8-bit address, while the data pointer (DPTR) register is used to specify the 16-bit address.
- Register Addressing: Certain instructions access one of the registers (R0 to R7) in the specified register bank. These instructions are more efficient because there is no need for an address field.
- Register Specific Instructions: Some instructions are specific to certain registers. For example, some instructions always act on the accumulator. In this case, there is no need to specify the operand.
- Immediate Constants: Some instructions carry the value of the constants directly instead of an address.
- Indexed Addressing: This type of addressing can be used only for a read of the program memory. This mode uses the Data Pointer as the base and the accumulator value as an offset to read a program memory.
- Bit Addressing: In this mode, the operand is one of 256 bits.

4.3 Instruction Set

The 8051 instruction set is highly optimized for 8-bit handling and Boolean operations. The types of instructions supported include:

- Arithmetic instructions
- Logical instructions
- Data transfer instructions
- Boolean instructions

Table 4-4. Boolean Instructions *(continued)*

Mnemonic	Description	Bytes	Cycles
ANL C, /bit	AND complement of direct bit to carry	2	2
ORL C, bit	OR direct bit to carry	2	2
ORL C, /bit	OR complement of direct bit to carry	2	2
MOV C, bit	Move direct bit to carry	2	2
MOV bit, C	Move carry to direct bit	2	3
JC rel	Jump if carry is set	2	3
JNC rel	Jump if no carry is set	2	3
JB bit, rel	Jump if direct bit is set	3	5
JNB bit, rel	Jump if direct bit is not set	3	5
JBC bit, rel	Jump if direct bit is set and clear bit	3	5

4.4.2 DMA Features

- 24 DMA channels
- Each channel has one or more transaction descriptors (TD) to configure channel behavior. Up to 128 total TDs can be defined
- TDs can be dynamically updated
- Eight levels of priority per channel
- Any digitally routable signal, the CPU, or another DMA channel, can trigger a transaction
- Each channel can generate up to two interrupts per transfer
- Transactions can be stalled or canceled
- Supports transaction size of infinite or 1 to 64 KB
- TDs may be nested and/or chained for complex transactions

4.4.3 Priority Levels

The CPU always has higher priority than the DMA controller when their accesses require the same bus resources. Due to the system architecture, the CPU can never starve the DMA. DMA channels of higher priority (lower priority number) may interrupt current DMA transfers. In the case of an interrupt, the current transfer is allowed to complete its current transaction. To ensure latency limits when multiple DMA accesses are requested simultaneously, a fairness algorithm guarantees an interleaved minimum percentage of bus bandwidth for priority levels 2 through 7. Priority levels 0 and 1 do not take part in the fairness algorithm and may use 100 percent of the bus bandwidth. If a tie occurs on two DMA requests of the same priority level, a simple round robin method is used to evenly share the allocated bandwidth. The round robin allocation can be disabled for each DMA channel, allowing it to always be at the head of the line.

Priority levels 2 to 7 are guaranteed the minimum bus bandwidth shown in Table 4-7 after the CPU and DMA priority levels 0 and 1 have satisfied their requirements.

Table 4-7. Priority Levels

Priority Level	% Bus Bandwidth
0	100.0
1	100.0
2	50.0
3	25.0
4	12.5
5	6.2
6	3.1
7	1.5

When the fairness algorithm is disabled, DMA access is granted based solely on the priority level; no bus bandwidth guarantees are made.

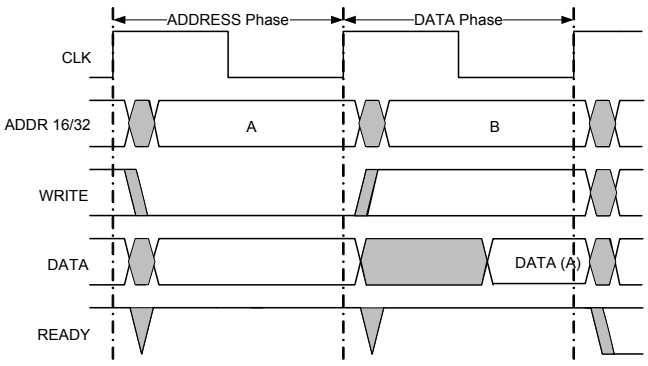
4.4.4 Transaction Modes Supported

The flexible configuration of each DMA channel and the ability to chain multiple channels allow the creation of both simple and complex use cases. General use cases include, but are not limited to:

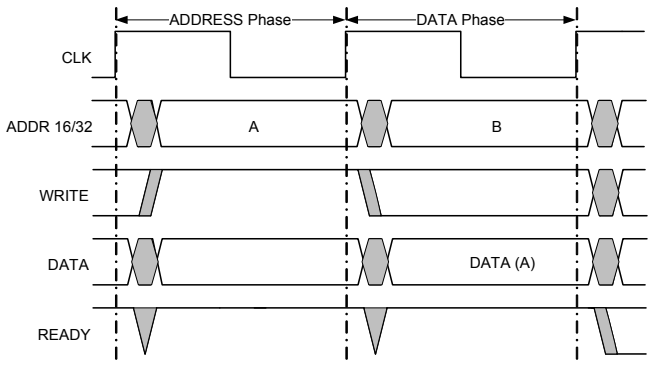
4.4.4.1 Simple DMA

In a simple DMA case, a single TD transfers data between a source and sink (peripherals or memory location). The basic timing diagrams of DMA read and write cycles are shown in Figure 4-1. For more description on other transfer modes, refer to the Technical Reference Manual.

Figure 4-1. DMA Timing Diagram



Basic DMA Read Transfer without wait states



Basic DMA Write Transfer without wait states

5.7.4 XData Space Access SFRs

The 8051 core features dual DPTR registers for faster data transfer operations. The data pointer select SFR, DPS, selects which data pointer register, DPTR0 or DPTR1, is used for the following instructions:

- MOVX @DPTR, A
- MOVX A, @DPTR
- MOVC A, @A+DPTR
- JMP @A+DPTR
- INC DPTR
- MOV DPTR, #data16

The extended data pointer SFRs, DPX0, DPX1, MXAX, and P2AX, hold the most significant parts of memory addresses during access to the xdata space. These SFRs are used only with the MOVX instructions.

During a MOVX instruction using the DPTR0/DPTR1 register, the most significant byte of the address is always equal to the contents of DPX0/DPX1.

During a MOVX instruction using the R0 or R1 register, the most significant byte of the address is always equal to the contents of MXAX, and the next most significant byte is always equal to the contents of P2AX.

5.7.5 I/O Port SFRs

The I/O ports provide digital input sensing, output drive, pin interrupts, connectivity for analog inputs and outputs, LCD, and access to peripherals through the DSI. Full information on I/O ports is found in I/O System and Routing on page 33.

I/O ports are linked to the CPU through the PHUB and are also available in the SFRs. Using the SFRs allows faster access to a limited set of I/O port registers, while using the PHUB allows boot configuration and access to all I/O port registers.

Each SFR supported I/O port provides three SFRs:

- SFRPRTxDR sets the output data state of the port (where × is port number and includes ports 0–6, 12 and 15).
- The SFRPRTxSEL selects whether the PHUB PRTxDR register or the SFRPRTxDR controls each pin's output buffer within the port. If a SFRPRTxSEL[y] bit is high, the corresponding SFRPRTxDR[y] bit sets the output state for that pin. If a SFRPRTxSEL[y] bit is low, the corresponding PRTxDR[y] bit sets the output state of the pin (where y varies from 0 to 7).
- The SFRPRTxPS is a read only register that contains pin state values of the port pins.

5.7.5.1 xdata Space

The 8051 xdata space is 24-bit, or 16 MB in size. The majority of this space is not 'external'—it is used by on-chip components. See Table 5-5. External, that is, off-chip, memory can be accessed using the EMIF. See External Memory Interface on page 23.

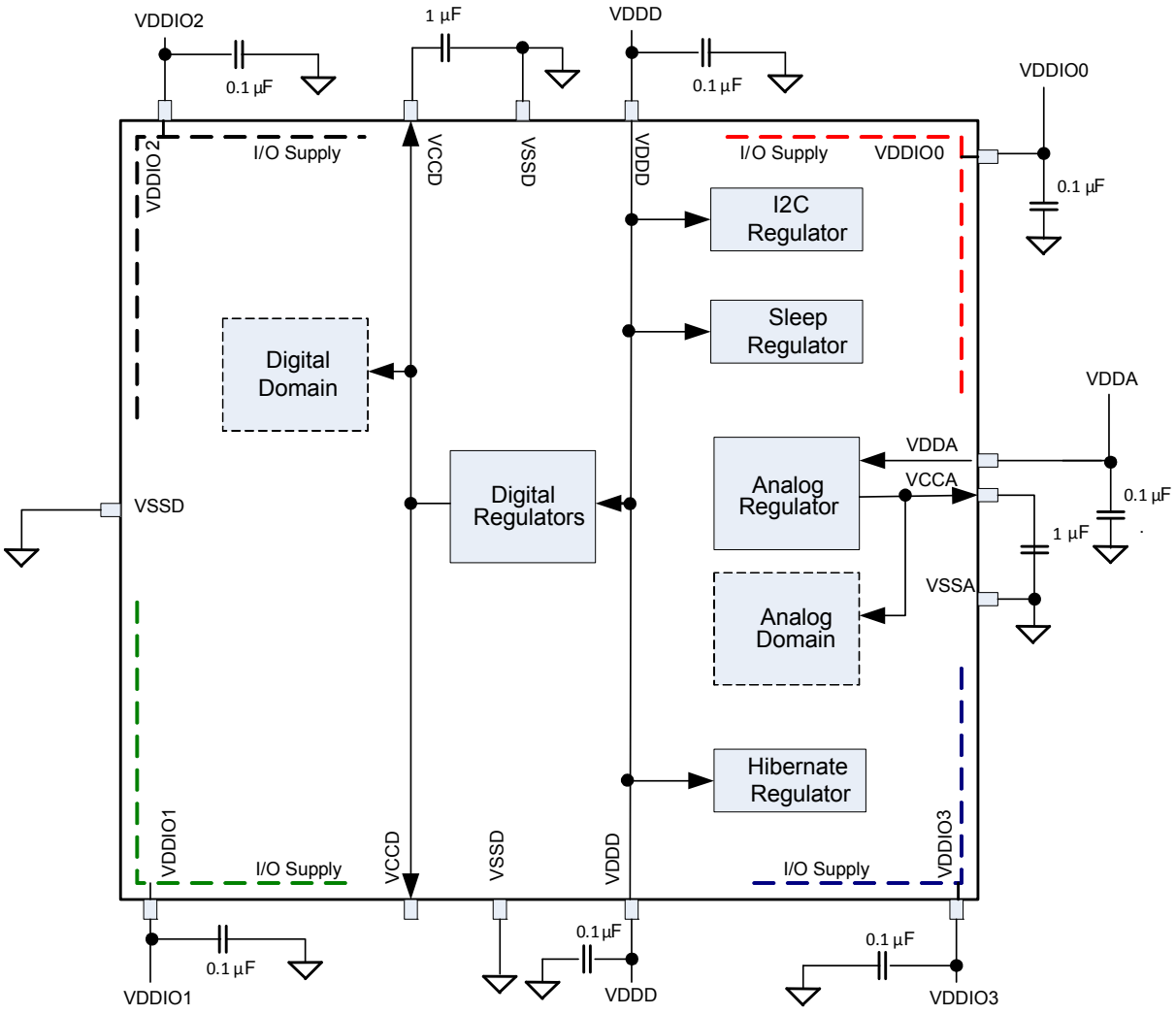
Table 5-5. XDATA Data Address Map

Address Range	Purpose
0×00 0000 – 0×00 1FFF	SRAM
0×00 4000 – 0×00 42FF	Clocking, PLLs, and oscillators
0×00 4300 – 0×00 43FF	Power management
0×00 4400 – 0×00 44FF	Interrupt controller
0×00 4500 – 0×00 45FF	Ports interrupt control
0×00 4700 – 0×00 47FF	Flash programming interface
0×00 4800 - 0×00 48FF	Cache controller
0×00 4900 – 0×00 49FF	I^2C controller
0×00 4E00 – 0×00 4EFF	Decimator
0×00 4F00 – 0×00 4FFF	Fixed timer/counter/PWMs
0×00 5000 – 0×00 51FF	I/O ports control
0×00 5400 – 0×00 54FF	EMIF control registers
0×00 5800 – 0×00 5FFF	Analog subsystem interface
0×00 6000 – 0×00 60FF	USB controller
0×00 6400 – 0×00 6FFF	UDB Working Registers
0×00 7000 – 0×00 7FFF	PHUB configuration
0×00 8000 – 0×00 8FFF	EEPROM
0×00 A000 – 0×00 A400	CAN
0×00 C000 – 0×00 C800	DFB
0×01 0000 – 0×01 FFFF	Digital Interconnect configuration
0×05 0220 – 0×05 02F0	Debug controller
0×08 0000 – 0×08 1FFF	Flash ECC bytes
0×80 0000 – 0×FF FFFF	External memory interface

6.2 Power System

The power system consists of separate analog, digital, and I/O supply pins, labeled VDDA, VDDD, and VDDIOX, respectively. It also includes two internal 1.8-V regulators that provide the digital (VCCD) and analog (VCCA) supplies for the internal core logic. The output pins of the regulators (VCCD and VCCA) and the VDDIO pins must have capacitors connected as shown in Figure 6-4. The two VCCD pins must be shorted together, with as short a trace as possible, and connected to a 1-µF ±10-percent X5R capacitor. The power system also contains a sleep regulator, an I^2C regulator, and a hibernate regulator.

Figure 6-4. PSoC Power System



Note The two VCCD pins must be connected together with as short a trace as possible. A trace under the device is recommended, as shown in Figure 2-6 on page 9.

You can power the device in internally regulated mode, where the voltage applied to the V_{DDx} pins is as high as 5.5 V, and the internal regulators provide the core voltages. **In this mode, do not apply power to the V_{CCx} pins, and do not tie the V_{DDx} pins to the V_{CCx} pins.**

You can also power the device in externally regulated mode, that is, by directly powering the V_{CCD} and V_{CCA} pins. In this configuration, the V_{DDD} pins should be shorted to the V_{CCD} pins and the V_{DDA} pin should be shorted to the V_{CCA} pin. The allowed supply range in this configuration is 1.71 V to 1.89 V. After power up in this configuration, the internal regulators are on by default, and should be disabled to reduce power consumption.

7. Digital Subsystem

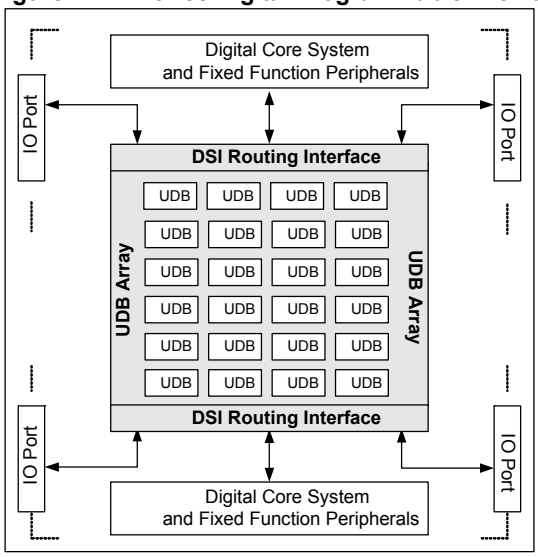
The digital programmable system creates application specific combinations of both standard and advanced digital peripherals and custom logic functions. These peripherals and logic are then interconnected to each other and to any pin on the device, providing a high level of design flexibility and IP security.

The features of the digital programmable system are outlined here to provide an overview of capabilities and architecture. You do not need to interact directly with the programmable digital system at the hardware and register level. PSoC Creator provides a high level schematic capture graphical interface to automatically place and route resources similar to PLDs.

The main components of the digital programmable system are:

- UDB – These form the core functionality of the digital programmable system. UDBs are a collection of uncommitted logic (PLD) and structural logic (Datapath) optimized to create all common embedded peripherals and customized functionality that are application or design specific.
- Universal digital block array – UDB blocks are arrayed within a matrix of programmable interconnect. The UDB array structure is homogeneous and allows for flexible mapping of digital functions onto the array. The array supports extensive and flexible routing interconnects between UDBs and the Digital System Interconnect.
- Digital system interconnect (DSI) – Digital signals from UDBs, fixed function peripherals, I/O pins, interrupts, DMA, and other system core signals are attached to the digital system interconnect to implement full featured device connectivity. The DSI allows any digital function to any pin or other feature routability when used with the universal digital block array.

Figure 7-1. CY8C38 Digital Programmable Architecture



7.1 Example Peripherals

The flexibility of the CY8C38 family's UDBs and analog blocks allow the user to create a wide range of components (peripherals). The most common peripherals were built and characterized by Cypress and are shown in the PSoC Creator component catalog, however, users may also create their own custom components using PSoC Creator. Using PSoC Creator, users may also create their own components for reuse within their organization, for example sensor interfaces, proprietary algorithms, and display interfaces.

The number of components available through PSoC Creator is too numerous to list in the data sheet, and the list is always growing. An example of a component available for use in CY8C38 family, but, not explicitly called out in this data sheet is the UART component.

7.1.1 Example Digital Components

The following is a sample of the digital components available in PSoC Creator for the CY8C38 family. The exact amount of hardware resources (UDBs, routing, RAM, flash) used by a component varies with the features selected in PSoC Creator for the component.

- Communications
  - I^2C
  - UART
  - SPI
- Functions
  - EMIF
  - PWMs
  - Timers
  - Counters
- Logic
  - NOT
  - OR
  - XOR
  - AND

7.1.2 Example Analog Components

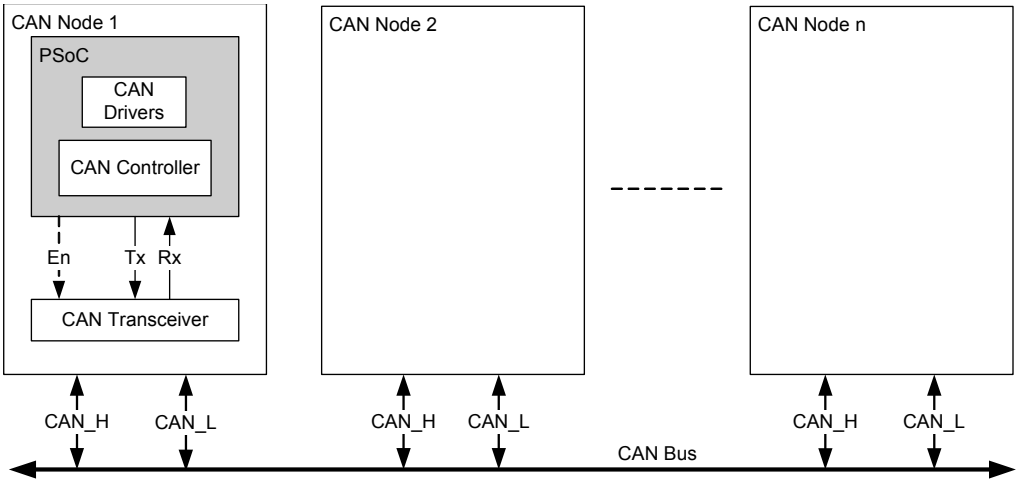
The following is a sample of the analog components available in PSoC Creator for the CY8C38 family. The exact amount of hardware resources (SC/CT blocks, routing, RAM, flash) used by a component varies with the features selected in PSoC Creator for the component.

- Amplifiers
  - TIA
  - PGA
  - opamp
- ADC
  - Delta-sigma
- DACs
  - Current
  - Voltage
  - PWM
- Comparators
- Mixers

7.5 CAN

The CAN peripheral is a fully functional controller area network (CAN) supporting communication baud rates up to 1 Mbps. The CAN controller implements the CAN2.0A and CAN2.0B specifications as defined in the Bosch specification and conforms to the ISO-11898-1 standard. The CAN protocol was originally designed for automotive applications with a focus on a high level of fault detection. This ensures high communication reliability at a low cost. Because of its success in automotive applications, CAN is used as a standard communication protocol for motion oriented machine control networks (CANOpen) and factory automation applications (DeviceNet). The CAN controller features allow the efficient implementation of higher level protocols without affecting the performance of the microcontroller CPU. Full configuration support is provided in PSoC Creator.

Figure 7-14. CAN Bus System Implementation



7.5.1 CAN Features

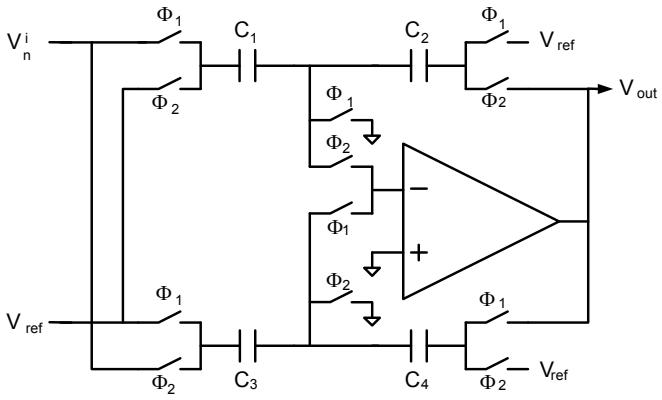
- CAN2.0A/B protocol implementation – ISO 11898 compliant
  - Standard and extended frames with up to 8 bytes of data per frame
  - Message filter capabilities
  - Remote Transmission Request (RTR) support
  - Programmable bit rate up to 1 Mbps
- Listen Only mode
- SW readable error counter and indicator
- Sleep mode: Wake the device from sleep with activity on the Rx pin
- Supports two or three wire interface to external transceiver (Tx, Rx, and Enable). The three-wire interface is compatible with the Philips PHY; the PHY is not included on-chip. The three wires can be routed to any I/O
- Enhanced interrupt controller
  - CAN receive and transmit buffers status
  - CAN controller error status including BusOff
- Receive path
  - 16 receive buffers each with its own message filter
  - Enhanced hardware message filter implementation that covers the ID, IDE, and RTR
  - DeviceNet addressing support
  - Multiple receive buffers linkable to build a larger receive message array
  - Automatic transmission request (RTR) response handler
  - Lost received message notification
- Transmit path
  - Eight transmit buffers
  - Programmable transmit priority
  - Round robin
  - Fixed priority
  - Message transmissions abort capability

7.5.2 Software Tools Support

CAN Controller configuration integrated into PSoC Creator:

- CAN Configuration walkthrough with bit timing analyzer
- Receive filter setup

Figure 8-13. Sample and Hold Topology (Φ1 and Φ2 are opposite phases of a clock)



8.11.1 Down Mixer

The SC/CT block can be used as a mixer to down convert an input signal. This circuit is a high bandwidth passive sample network that can sample input signals up to 14 MHz. This sampled value is then held using the opamp with a maximum clock rate of 4 MHz. The output frequency is at the difference between the input frequency and the highest integer multiple of the Local Oscillator that is less than the input.

8.11.2 First Order Modulator – SC Mode

A first order modulator is constructed by placing the SC/CT block in an integrator mode and using a comparator to provide a 1-bit feedback to the input. Depending on this bit, a reference voltage is either subtracted or added to the input signal. The block output is the output of the comparator and not the integrator in the modulator case. The signal is downshifted and buffered and then processed by a decimator to make a delta-sigma converter or a counter to make an incremental converter. The accuracy of the sampled data from the first-order modulator is determined from several factors.

The main application for this modulator is for a low-frequency ADC with high accuracy. Applications include strain gauges, thermocouples, precision voltage, and current measurement.

9. Programming, Debug Interfaces, Resources

PSoC devices include extensive support for programming, testing, debugging, and tracing both hardware and firmware. Three interfaces are available: JTAG, SWD, and SWV. JTAG and SWD support all programming and debug features of the device. JTAG also supports standard JTAG scan chains for board level test and chaining multiple JTAG devices to a single JTAG connection.

For more information on PSoC 3 Programming, refer to the PSoC® 3 Device Programming Specifications.

Complete Debug on Chip (DoC) functionality enables full device debugging in the final system using the standard production device. It does not require special interfaces, debugging pods, simulators, or emulators. Only the standard programming connections are required to fully support debug.

The PSoC Creator IDE software provides fully integrated programming and debug support for PSoC devices. The low cost MiniProg3 programmer and debugger is designed to provide full programming and debug support of PSoC devices in conjunction with the PSoC Creator IDE. PSoC JTAG, SWD, and SWV interfaces are fully compatible with industry standard third party tools.

All DOC circuits are disabled by default and can only be enabled in firmware. If not enabled, the only way to reenable them is to erase the entire device, clear flash protection, and reprogram the device with new firmware that enables DOC. Disabling DOC features, robust flash protection, and hiding custom analog and digital functionality inside the PSoC device provide a level of security not possible with multichip application solutions. Additionally, all device interfaces can be permanently disabled (Device Security) for applications concerned about phishing attacks due to a maliciously reprogrammed device. Permanently disabling interfaces is not recommended in most applications because you cannot access the device later. Because all programming, debug, and test interfaces are disabled when device security is enabled, PSoCs with Device Security enabled may not be returned for failure analysis.

Table 9-1. Debug Configurations

Debug and Trace Configuration	GPIO Pins Used
All debug and trace disabled	0
JTAG	4 or 5
SWD	2
SWV	1
SWD + SWV	3

9.1 JTAG Interface

The IEEE 1149.1 compliant JTAG interface exists on four or five pins (the nTRST pin is optional). The JTAG interface is used for programming the flash memory, debugging, I/O scan chains, and JTAG device chaining.

PSoC 3 has certain timing requirements to be met for entering programming mode through the JTAG interface. Due to these timing requirements, not all standard JTAG programmers, or standard JTAG file formats such as SVF or STAPL, can support PSoC 3 programming. The list of programmers that support PSoC 3 programming is available at http://www.cypress.com/go/programming.

The JTAG clock frequency can be up to 14 MHz, or 1/3 of the CPU clock frequency for 8 and 16-bit transfers, or 1/5 of the CPU clock frequency for 32-bit transfers. By default, the JTAG pins are enabled on new devices but the JTAG interface can be disabled, allowing these pins to be used as GPIO instead.

11. Electrical Specifications

Specifications are valid for -40°C ≤ Ta ≤ 125°C and Tj ≤ 150°C, except where noted. Specifications are valid for 1.71 V to 5.5 V, except where noted. The unique flexibility of the PSoC UDBs and analog blocks enable many functions to be implemented in PSoC Creator components, see the component data sheets for full AC/DC specifications of individual functions. See the Example Peripherals on page 40 for further explanation of PSoC Creator components.

11.1 Absolute Maximum Ratings

Table 11-1. Absolute Maximum Ratings DC Specifications [18]

Parameter	Description	Conditions	Min	Typ	Max	Units
Tstorag	Storage temperature	Recommended storage temperature is 0 °C–50 °C. Exposure to storage temperatures above 125 °C for extended periods may affect device reliability	–55	25	125	°C
Vdda	Analog supply voltage relative to Vssd		–0.5	–	6	V
Vddd	Digital supply voltage relative to Vssd		–0.5	–	6	V
Vddio	I/O supply voltage relative to Vssd		–0.5	–	6	V
Vcca	Direct analog core voltage input		–0.5	–	1.95	V
Vccd	Direct digital core voltage input		–0.5	–	1.95	V
Vssa	Analog ground voltage		Vssd – 0.5	–	Vssd + 0.5	V
Vgpio[19]	DC input voltage on GPIO	Includes signals sourced by Vdda and routed internal to the pin	Vssd – 0.5	–	Vddio + 0.5	V
Vsio	DC input voltage on SIO	Output disabled	Vssd – 0.5	–	7	V
		Output enabled	Vssd – 0.5	–	6	V
Ivddio [20]	Current per Vddio supply pin	–40 °C to +85 °C	–	–	100	mA
		–40 °C to +125 °C	–	–	40	
I_{GPIO}	GPIO current		–30	–	41	mA
I_{SIO}	SIO current		–49	–	28	mA
I_{USBIO}	USBIO current		–56	–	59	mA
V_{EXTREF}	ADC external reference inputs	Pins P0[3], P3[2]	–	–	2	V
LU	Latch up current [21]		–140	–	140	mA
ESD_{HBM}	Electrostatic discharge voltage, Human body model	V_{SSA} tied to V_{SSD}	2200	–	–	V
		V_{SSA} not tied to V_{SSD}	750	–	–	V
ESD_{CDM}	Electro-static discharge voltage	Charge Device Model	500	–	–	V

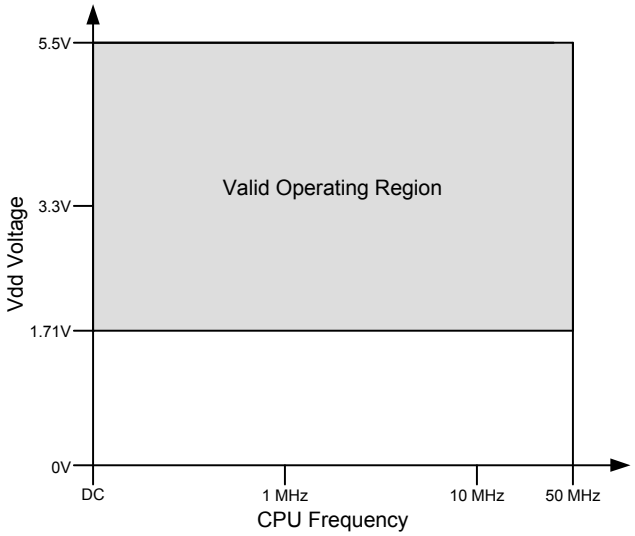
Note Usage above the absolute maximum conditions listed in Table 11-1 may cause permanent damage to the device. Exposure to maximum conditions for extended periods of time may affect device reliability. When used below maximum conditions but above normal operating conditions the device may not operate to specification.

Notes
18. Usage above the absolute maximum conditions listed in Table 11-1 may cause permanent damage to the device. Exposure to Absolute Maximum conditions for extended periods of time may affect device reliability. The Maximum Storage Temperature is 150 °C in compliance with JEDEC Standard JESD22-A103, High Temperature Storage Life. When used below Absolute Maximum conditions but above normal operating conditions, the device may not operate to specification.
19. The Vddio supply voltage must be greater than the maximum analog voltage on the associated GPIO pins. Maximum analog voltage on GPIO pin ≤ Vddio ≤ Vdda.
20. Maximum value 100 mA of Iddio applies only to –40 °C to +85 °C range and the limit of Iddio parameter for the –40 °C to +125 °C range is 40 mA.
21. Meets or exceeds JEDEC Spec EIA/JESD78 IC Latch-up Test.

Table 11-3. AC Specifications[30]

Parameter	Description	Conditions	Min	Typ	Max	Units
F_{CPU}	CPU frequency	1.71 V ≤ Vddd ≤ 5.5 V, -40°C ≤ Ta ≤ 85°C and Tj ≤ 100°C	DC	–	67	MHz
		1.71 V ≤ Vddd ≤ 5.5 V, -40°C ≤ Ta ≤ 125°C and Tj ≤ 150°C	DC	–	50	MHz
F_{busclk}	Bus frequency	1.71 V ≤ Vddd ≤ 5.5 V, -40°C ≤ Ta ≤ 85°C and Tj ≤ 100°C	DC	–	67	MHz
		1.71 V ≤ Vddd ≤ 5.5 V, -40°C ≤ Ta ≤ 125°C and Tj ≤ 150°C	DC	–	50	MHz
Svdd	Vdd ramp rate		–	–	0.066	V/µs
Tio_init	Time from Vddd/Vdda/Vccd/Vcca ≥ IPOR to I/O ports set to their reset states		–	–	10	µs
Tstartup	Time from Vddd/Vdda/Vccd/Vcca ≥ PRES to CPU executing code at reset vector	Vcca/Vdda = regulated from Vdda/Vddd, no PLL used, fast IMO boot mode (48 MHz typ.)	–	–	40	µs
		Vcca/Vccd = regulated from Vdda/Vddd, no PLL used, slow IMO boot mode (12 MHz typ.)	–	–	74	µs
Tsleep	Wakeup from sleep mode - Occurrence of LVD interrupt to beginning of execution of next CPU instruction	1.71 V ≤ Vddd ≤ 5.5 V, Tj ≤ 100°C	–	–	15	µs
Thibernate	Wakeup from hibernate mode - Application of external interrupt to beginning of execution of next CPU instruction		–	–	100	µs

Figure 11-2. Fcpu vs. Vdd



Note
30. Based on device characterization (not production tested).

Figure 11-6. GPIO Output High Voltage and Current

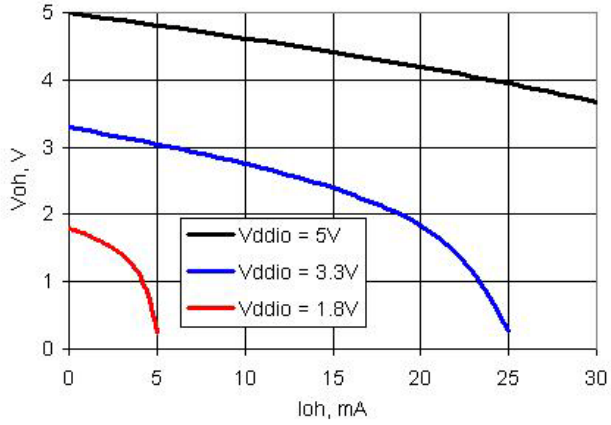
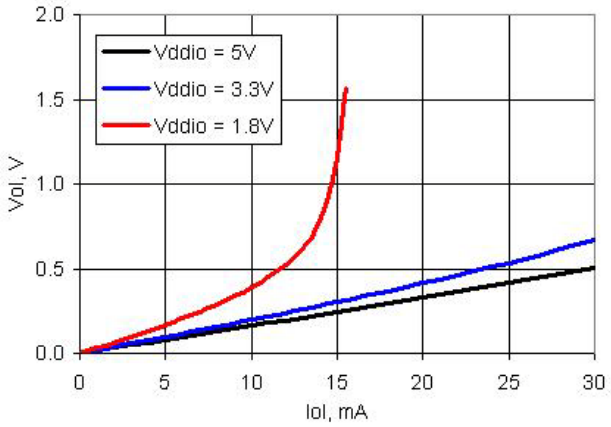


Figure 11-7. GPIO Output Low Voltage and Current



11.5 Analog Peripherals

Specifications are valid for -40°C ≤ Ta ≤ 125°C and Tj ≤ 150°C, except where noted. Specifications are valid for 1.71 V to 5.5 V, except where noted.

11.5.1 Opamp

Table 11-15. Opamp DC Specifications

Parameter	Description	Conditions	Min	Typ	Max	Units
Vioff	Input offset voltage	-40°C ≤ Ta ≤ 85°C and Tj ≤ 100°C	-	-	±2.5	mV
		-40°C ≤ Ta ≤ 125°C and Tj ≤ 150°C	-	-	±5.0	mV
TCVos	Input offset voltage drift with temperature	Power mode = high	–	–	±30	µV / °C
Ge1	Gain error, unity gain buffer mode	Rload = 1 kΩ	-	-	±0.1	%
Vi	Input voltage range		Vssa	-	Vdda	mV
Vo	Output voltage range	Output load = 1 mA	Vssa + 50	-	Vdda - 50	mV
Iout	Output current	Output voltage is between Vssa +500 mV and Vdda -500 mV, and Vdda > 2.7 V, -40°C ≤ Ta ≤ 85°C and Tj ≤ 100°C	25	-	-	mA
		Output voltage is between Vssa +500 mV and Vdda -500 mV, and Vdda > 2.7 V, -40°C ≤ Ta ≤ 125°C and Tj ≤ 150°C	20	-	-	mA
Iout	Output current	Output voltage is between Vssa +500 mV and Vdda -500 mV, and Vdda > 1.7 V and Vdda < 2.7 V	16	-	-	mA
I_{DD}	Quiescent current	Power mode = min	–	250	400	µA
		Power mode = low	–	250	400	µA
		Power mode = med	–	330	950	µA
		Power mode = high	–	1000	2500	µA
CMRR	Common mode rejection ratio[30]		80	–	–	dB
PSRR	Power supply rejection ratio	Vdda ≥ 2.7 V	85	–	–	dB
		Vdda < 2.7 V	70	–	–	dB

Figure 11-16. Opamp Voffset Histogram, 3388 samples/847 parts, 25 °C, Vdda = 5 V

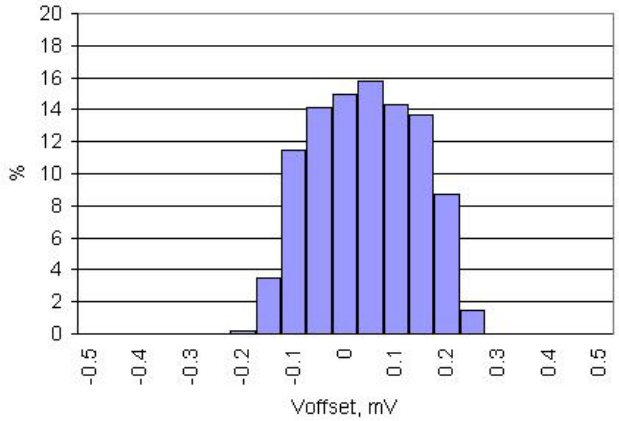


Table 11-18. Delta-sigma ADC AC Specifications

Parameter	Description	Conditions	Min	Typ	Max	Units
	Startup time		–	–	4	Samples
THD	Total harmonic distortion[38]	Buffer gain = 1, 16 bit, Range = ±1.024 V	–	–	0.0040	%
20-Bit Resolution Mode						
SR20	Sample rate[38]	Range = ±1.024 V, unbuffered	7.8	–	187	sps
BW20	Input bandwidth at max sample rate[38]	Range = ±1.024 V, unbuffered	–	40	–	Hz
16-Bit Resolution Mode						
SR16	Sample rate[38]	Range = ±1.024 V, unbuffered	2	–	48	ksps
BW16	Input bandwidth at max sample rate[38]	Range = ±1.024 V, unbuffered	–	11	–	kHz
SINAD16int	Signal to noise ratio, 16-bit, internal reference[38]	Range = ±1.024V, unbuffered	79	–	–	dB
SINAD16ext	Signal to noise ratio, 16-bit, external reference[38]	Range = ±1.024 V, unbuffered	83	–	–	dB
12-Bit Resolution Mode						
SR12	Sample rate, continuous, high power[38]	Range = ±1.024 V, unbuffered	4	–	192	ksps
BW12	Input bandwidth at max sample rate[38]	Range = ±1.024 V, unbuffered	–	44	–	kHz
SINAD12int	Signal to noise ratio, 12-bit, internal reference[38]	Range = ±1.024 V, unbuffered	66	–	–	dB
8-Bit Resolution Mode						
SR8	Sample rate, continuous, high power[38]	Range = ±1.024 V, unbuffered	8	–	384	ksps
BW8	Input bandwidth at max sample rate[38]	Range = ±1.024 V, unbuffered	–	88	–	kHz
SINAD8int	Signal to noise ratio, 8-bit, internal reference[38]	Range = ±1.024 V, unbuffered	43	–	–	dB

Table 11-19. Delta-sigma ADC Sample Rates, Range = ±1.024 V

Resolution, Bits	Continuous		Multi-Sample		Multi-Sample Turbo	
	Min	Max	Min	Max	Min	Max
8	8000	384000	1911	91701	1829	87771
9	6400	307200	1543	74024	1489	71441
10	5566	267130	1348	64673	1307	62693
11	4741	227555	1154	55351	1123	53894
12	4000	192000	978	46900	956	45850
13	3283	157538	806	38641	791	37925
14	2783	133565	685	32855	674	32336
15	2371	113777	585	28054	577	27675
16	2000	48000	495	11861	489	11725
17	500	12000	124	2965	282	6766
18	125	3000	31	741	105	2513
19	16	375	4	93	15	357
20	8	187.5	2	46	8	183

Figure 11-24. Delta-sigma ADC IDD vs sps, Range = ±1.024 V, Continuous Sample Mode, Input Buffer Bypassed

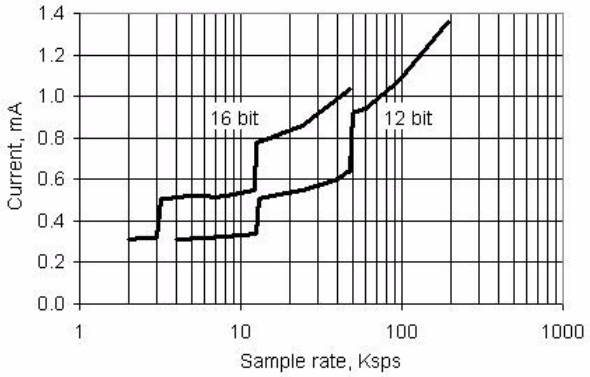


Figure 11-25. Delta-sigma ADC Noise Histogram, 1000 Samples, 20-Bit, 187 sps, Ext Ref, $V_{IN} = V_{REF}/2$, Range = ±1.024 V

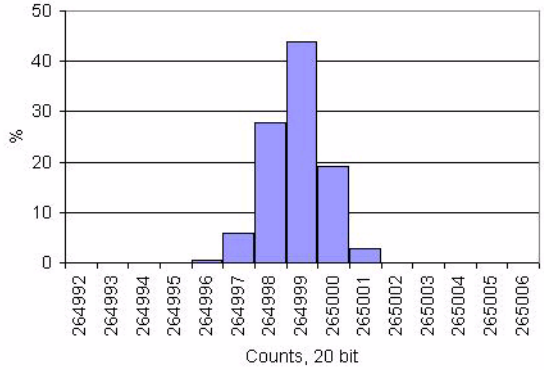


Figure 11-26. Delta-sigma ADC Noise Histogram, 1000 Samples, 16-bit, 48 ksps, Ext Ref, $V_{IN} = V_{REF}/2$, Range = ±1.024 V

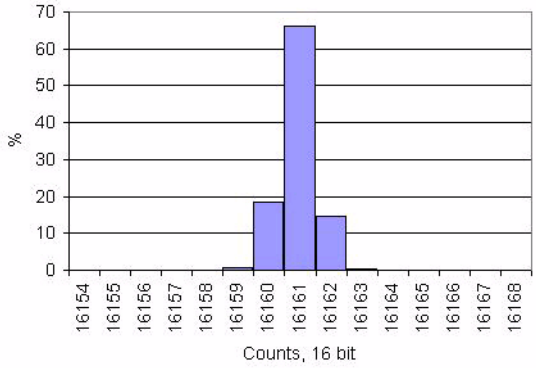


Figure 11-50. VDAC Full Scale Error vs Temperature, 1 V Mode

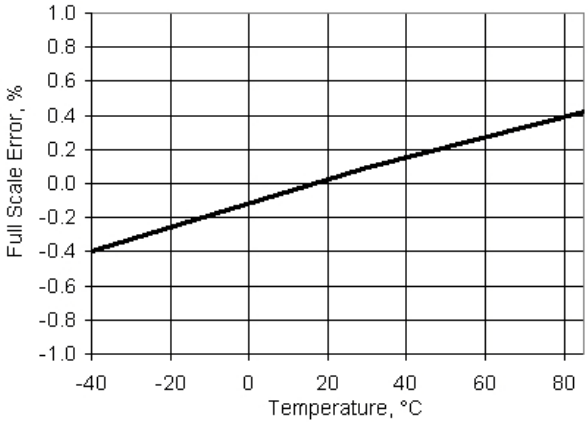


Figure 11-51. VDAC Full Scale Error vs Temperature, 4 V Mode

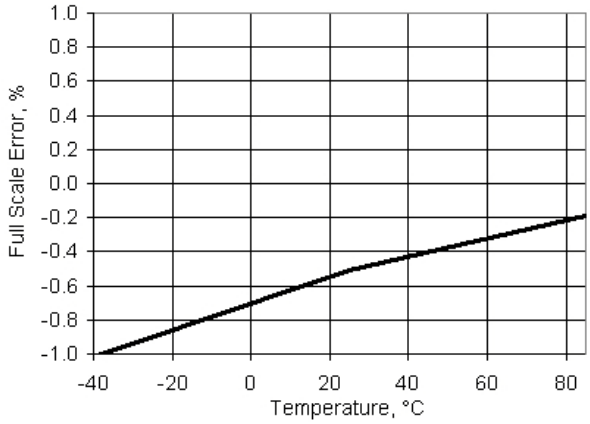
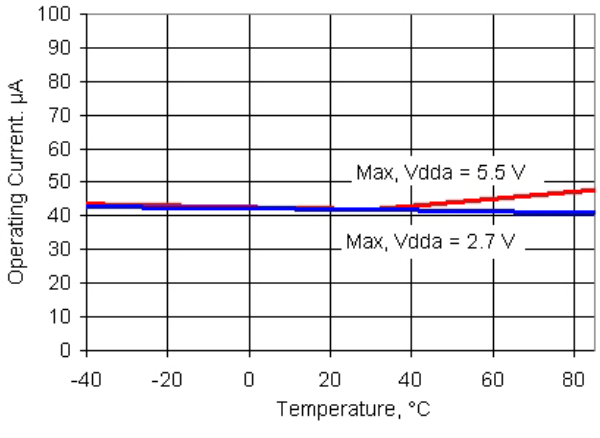


Figure 11-52. VDAC Operating Current vs Temperature, 1V Mode, Low speed mode



11.6.4 I^2C

Table 11-47. Fixed I^2C DC Specifications

Parameter	Description	Conditions	Min	Typ	Max	Units
	Block current consumption	Enabled, configured for 100 kbps	–	–	250	µA
	–	Enabled, configured for 400 kbps	–	–	260	µA
	–	Wake from sleep mode	–	–	30	µA

Table 11-48. Fixed I^2C AC Specifications

Parameter	Description	Conditions	Min	Typ	Max	Units
	Bit rate		-	-	1	Mbps

11.6.5 Controller Area Network[50]

Table 11-49. CAN DC Specifications

Parameter	Description	Conditions	Min	Typ	Max	Units
	Block current consumption	500 kbps	-	-	285	µA
		1 Mbps	-	-	330	µA

Table 11-50. CAN AC Specifications

Parameter	Description	Conditions	Min	Typ	Max	Units
	Bit rate	Minimum 8 MHz clock	-	-	1	Mbit

11.6.6 Digital Filter Block

Table 11-51. DFB DC Specifications

Parameter	Description	Conditions	Min	Typ	Max	Units
	DFB operating current	64-tap FIR at Fdfb				
		500 kHz (6.7 ksps)	-	0.16	0.27	mA
		1 MHz (13.4 ksps)	-	0.33	0.53	mA
		10 MHz (134 ksps)	-	3.3	5.3	mA
		50 MHz (644 ksps)	-	15.7	25.5	mA
		67 MHz (900 ksps)[51]	-	21.8	35.6	mA

Table 11-52. DFB AC Specifications

Parameter	Description	Conditions	Min	Typ	Max	Units
Fdfb	DFB operating frequency	-40°C ≤ Ta ≤ 85°C and Tj ≤ 100°C	DC	-	67 [51]	MHz
		-40°C ≤ Ta ≤ 125°C and Tj ≤ 150°C	DC	-	50 [51]	MHz

Note
50. Refer to ISO 11898 specification for details.
51. Applicable at -40°C to 85°C; 50 MHz at -40°C to 125°C.

11.9.3 External Crystal Oscillator

Table 11-79. 32 kHz External Crystal DC Specifications[66]

Parameter	Description	Conditions	Min	Typ	Max	Units
Icc	Operating current	Low power mode; C_L = 6 pF; -40°C ≤ Ta ≤ 125°C and Tj ≤ 150°C	–	0.25	1.0	µA
DL	Drive level	Low-power mode; C_L = 6 pF	–	–	1	µW

Table 11-80. 32 kHz External Crystal AC Specifications

Parameter	Description	Conditions	Min	Typ	Max	Units
F	Frequency		–	32.768	–	kHz
Ton	Startup time	High power mode	–	1	–	s

Table 11-81. MHz ECO AC Specifications

Parameter	Description	Conditions	Min	Typ	Max	Units
F	Crystal frequency range		4	–	25	MHz

11.9.4 External Clock Reference

Table 11-82. External Clock Reference AC Specifications

Parameter	Description	Conditions	Min	Typ	Max	Units
	External frequency range		0	–	33	MHz
	Input duty cycle range	Measured at V_{DDIO}/2	30	50	70	%
	Input edge rate	V_{IL} to V_{IH}	0.51	–	–	V/ns

11.9.5 Phase-Locked Loop

Table 11-83. PLL DC Specifications

Parameter	Description	Conditions	Min	Typ	Max	Units
I_{DD}	PLL operating current	In = 3 MHz, Out = 67 MHz	–	400	–	µA
		In = 3 MHz, Out = 24 MHz	–	200	–	µA

Table 11-84. PLL AC Specifications

Parameter	Description	Conditions	Min	Typ	Max	Units
Fpllin	PLL input frequency[67]	Output of Prescalar	1	-	48	MHz
	PLL intermediate frequency[68]		1	-	3	MHz
Fpllout	PLL output frequency[67]	-40°C ≤ Ta ≤ 85°C and Tj ≤ 100°C	24	-	67	MHz
		-40°C ≤ Ta ≤ 125°C and Tj ≤ 150°C	24	-	50	MHz
	Lock time at startup		-	-	250	µs
Jperiod-rms	Jitter (rms)[30]	-40°C ≤ Ta ≤ 85°C and Tj ≤ 100°C	-	-	250	ps
		-40°C ≤ Ta ≤ 125°C and Tj ≤ 150°C	-	-	400	ps

Notes
66. Based on device characterization (not production tested).
67. This specification is guaranteed by testing the PLL across the specified range using the IMO as the source for the PLL.
68. PLL input divider, Q, must be set so that the input frequency is divided down to the intermediate frequency range. Value for Q ranges from 1 to 16.

12. Ordering Information

In addition to the features listed in Table 12-1, every CY8C38 device includes: a precision on-chip voltage reference, precision oscillators, Flash, ECC, DMA, a fixed function I^2C, 4 KB trace RAM, JTAG/SWD programming and debug, external memory interface, and more. In addition to these features, the flexible UDBs and Analog Subsection support a wide range of peripherals. To assist you in selecting the ideal part, PSoC Creator makes a part recommendation after you choose the components required by your application. All CY8C38 derivatives incorporate device and Flash security in user-selectable security levels; see TRM for details.

Table 12-1. CY8C38 Family with Single Cycle 8051

Part Number	MCU Core				Analog								Digital				I/O[70]				Package	JTAG ID[71]
	CPU Speed (MHz)	Flash (KB)	SRAM (KB)	EEPROM (KB)	LCD Segment Drive	ADC	DAC	Comparator	SC/CT Analog Blocks	Opamps	DFB	CapSense	UDBs[69]	16-bit Timer/PWM	FS USB	CAN 2.0b	Total I/O	GPIO	SIO	USBIO		
32 KB Flash																						
CY8C3845PVE-173	50	32	4	1	-	20-bit Del-Sig	4	4	4	2	✔	✔	20	4	-	-	29	25	4	0	48-SSOP	0x1E0AD069
CY8C3865AXA-018	67	32	4	1	✔	20-bit Del-Sig	4	4	4	4	✔	✔	20	4	-	-	70	62	8	0	100-TQFP	0x1E012069
CY8C3865AXA-019	67	32	4	1	✔	20-bit Del-Sig	4	4	4	4	✔	✔	20	4	✔	-	72	62	8	2	100-TQFP	0x1E013069
CY8C3865PVA-060	67	32	4	1	✔	20-bit Del-Sig	4	4	4	2	✔	✔	20	4	-	-	29	25	4	0	48-SSOP	0x1E03C069
CY8C3865PVA-063	67	32	4	1	✔	20-bit Del-Sig	4	4	4	2	✔	✔	20	4	✔	-	31	25	4	2	48-SSOP	0x1E03F069
64 KB Flash																						
CY8C3846AXE-175	50	64	8	2	-	20-bit Del-Sig	4	4	4	4	✔	✔	24	4	-	✔	70	62	8	0	100-TQFP	0x1E0AF069
CY8C3846AXE-176	50	64	8	2	✔	20-bit Del-Sig	4	4	4	4	✔	✔	24	4	✔	✔	72	62	8	2	100-TQFP	0x1E0B0069
CY8C3846PVE-174	50	64	8	2	-	20-bit Del-Sig	4	4	4	2	✔	✔	24	4	-	✔	29	25	4	0	48-SSOP	0x1E0AE069
CY8C3866AXA-035	67	64	8	2	✔	20-bit Del-Sig	4	4	4	4	✔	✔	24	4	-	✔	70	62	8	0	100-TQFP	0x1E023069
CY8C3866AXA-038	67	64	8	2	✔	20-bit Del-Sig	4	4	4	4	✔	✔	24	4	-	-	70	62	8	0	100-TQFP	0x1E026069
CY8C3866AXA-039	67	64	8	2	✔	20-bit Del-Sig	4	4	4	4	✔	✔	24	4	✔	-	72	62	8	2	100-TQFP	0x1E027069
CY8C3866AXA-040	67	64	8	2	✔	20-bit Del-Sig	4	4	4	4	✔	✔	24	4	✔	✔	72	62	8	2	100-TQFP	0x1E028069
CY8C3866AXA-055	67	64	8	2	-	20-bit Del-Sig	4	4	4	4	✔	✔	24	4	-	✔	70	62	8	0	100-TQFP	0x1E037069
CY8C3866PVA-005	67	64	8	2	-	20-bit Del-Sig	4	4	4	2	✔	✔	24	4	-	-	29	25	4	0	48-SSOP	0x1E005069
CY8C3866PVA-021	67	64	8	2	-	20-bit Del-Sig	4	4	4	2	✔	✔	24	4	✔	-	31	25	4	2	48-SSOP	0x1E015069
CY8C3866PVA-047	67	64	8	2	-	20-bit Del-Sig	4	4	4	2	✔	✔	24	4	-	✔	29	25	4	0	48-SSOP	0x1E02F069
CY8C3866PVA-070	67	64	8	2	✔	20-bit Del-Sig	4	4	4	2	✔	✔	24	4	-	✔	29	25	4	0	48-SSOP	0x1E046069

Notes

69. UDBs support a wide variety of functionality including SPI, LIN, UART, timer, counter, PWM, PRS, and others. Individual functions may use a fraction of a UDB or multiple UDBs. Multiple functions can share a single UDB. See the "Example Peripherals" section on page 40 for more information on how UDBs may be used.
70. The I/O Count includes all types of digital I/O: GPIO, SIO, and the two USB I/O. See the ""I/O System and Routing" section on page 33" for details on the functionality of each of these types of I/O.
71. The JTAG ID has three major fields. The most significant nibble (left digit) is the version, followed by a 2 byte part number and a 3 nibble manufacturer ID.

17. Revision History *(continued)*

Description Title: PSoC® 3: CY8C38 Automotive Family Datasheet, Programmable System-on-Chip (PSoC®) Document Number: 001-54683				
Rev.	**ECN**	**Submission Date**	**Orig. of Change**	**Description of Change**
*H (cont.)	4094193	08/30/2013	NFB / ANMD	Updated Electrical Specifications: Updated Device Level Specifications: Updated Table 11-2. Updated Table 11-3. Updated Inputs and Outputs: Updated GPIO: Updated Table 11-7. Removed figure “GPIO Output Rise and Fall Times, Fast Strong Mode, V_{DDIO} = 3.3 V, 25 pF Load” and figure “GPIO Output Rise and Fall Times, Slow Strong Mode, V_{DDIO} = 3.3 V, 25 pF Load”. Updated Analog Peripherals: Updated Delta-Sigma ADC: Updated Table 11-17. Updated Table 11-18. Updated Voltage Reference: Updated Table 11-24. Updated IDAC: Updated Table 11-28. Updated Memory: Updated Flash: Updated Table 11-56. Updated Clocking: Updated Internal Main Oscillator: Updated Table 11-76. Updated Packaging: spec 51-85048 – Changed revision from *G to *H. Updated in new template. Completing Sunset Review.
*I	4174912	10/26/2013	NFB / ANMD	Updated Pinouts: Added Note 8 and referred the same note in 100 mA in description. Updated Electrical Specifications: Updated Absolute Maximum Ratings: Updated Table 11-1. Added Note 18 and referred the same note in Table 11-1. Added Note 20 and referred the same note in Ivddio parameter in Table 11-1. Updated Device Level Specifications: Updated Table 11-2. Updated Analog Peripherals: Updated Opamp: Updated Table 11-15. Updated Voltage Reference: Updated Table 11-24. Updated Packaging: Updated Table 13-1.
*J	4188568	11/14/2013	WKA	No content update.

18. Sales, Solutions, and Legal Information

Worldwide Sales and Design Support

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